

Title (en)

METHOD OF COATING FINE WIRES AND CURABLE COMPOSITION THEREFOR

Title (de)

VERFAHREN ZUR BESCHICHTUNG VON FEINEN DRÄHTEN UND AUSHÄRTBARE ZUSAMMENSETZUNG DAFÜR

Title (fr)

PROCÉDÉ DE REVÊTEMENT DE FILS FINS ET COMPOSITION DURCISSABLE À CET EFFET

Publication

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Application

EP 08862170 A 20081113

Priority

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Abstract (en)

[origin: WO2009079122A1] A method of reducing wire sweep and shorting during fabrication of a semiconductor device includes spraying a curable composition onto wire bonds, and free-radically B-staging the curable composition, and then thermal curing to a C-stage. A sprayable curable composition is also disclosed.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 2009079122A1

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